

FEATURES

- **HIGH ISOLATION VOLTAGE**
BV: 5 k Vr.m.s. MIN
- **HIGH PROPAGATION DELAY TIME**
tPHL, tPLH: 50 ns TYP
- **LOW INPUT CURRENT**
IFHL: 2.5 mA TYP
- **CAN BE SOLDERED BY INFRARED REFLOW SOLDERING**
- **TAPING PRODUCT NUMBER PS9601L-E3, E4**



DESCRIPTION

PS9601 and PS9601L are optically coupled isolators containing a GaAlAs LED on the light emitting side (input side), and a photodiode and a signal processing circuit on the light receiving side (output side), on one chip. PS9601 is in a plastic DIP (Dual In-Line Package) and PS9601L is in a lead bending type (Gull-wing) for surface mount.

APPLICATIONS

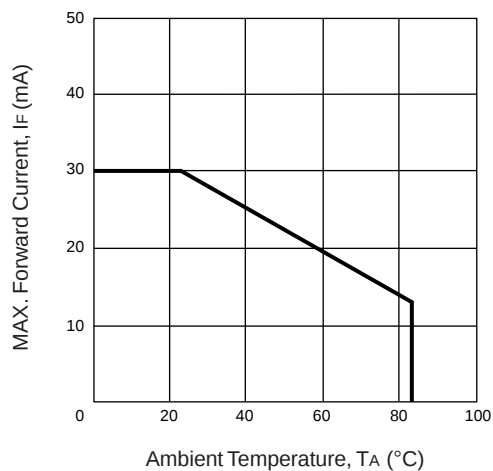
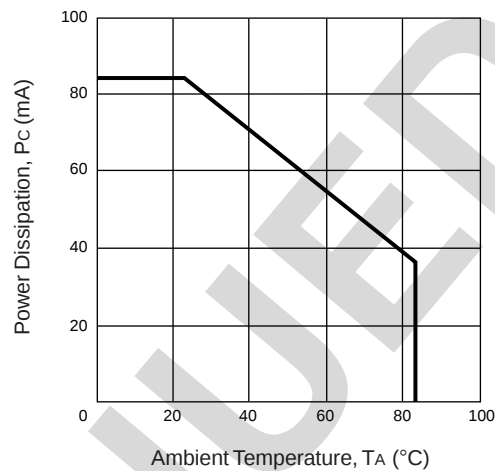
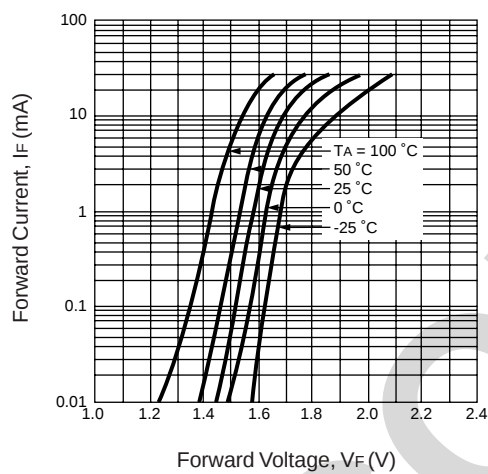
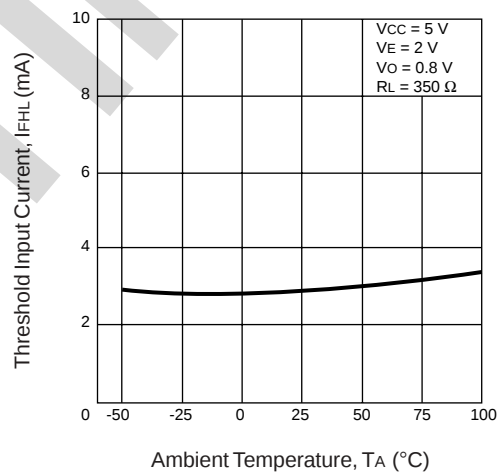
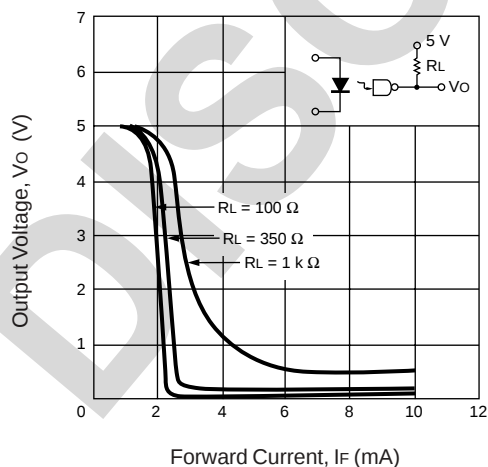
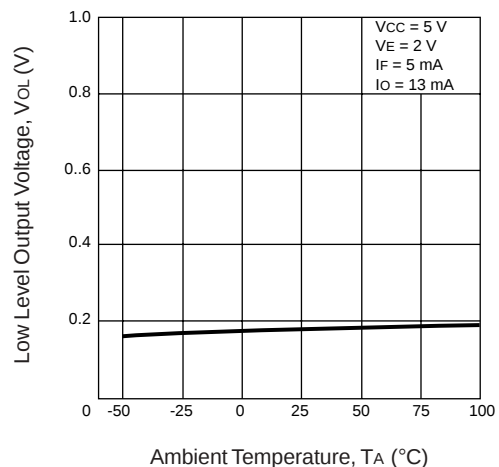
- **COMPUTER AND PERIPHERAL MEMORY**
- **ELECTRONIC INSTRUMENT**
- **AUDIO-VISUAL**

ELECTRICAL CHARACTERISTICS (TA = -40 to +85 °C)

PART NUMBER			PS9601, PS9601L		
SYMBOLS	PARAMETERS	UNITS	MIN	TYP	MAX
Diode	VF	Forward Voltage, IF = 10 mA, TA = 25 °C	V	1.4	1.9
	IR	Reverse Current, VR = 5 V, TA = 25 °C	μA		10
	Ct	Capacitance, V = 0, f = 1 MHz, TA = 25 °C	pF	60	
Detector	IOH	High Level Output Current VCC = VO = 5.5 V, IF = 250 μs, VE = 2 V	μA	2	250
	VOL	Low Level Output Voltage VCC = 5.5 V, IF = 5 mA, VE = 2 V, IO = 13 mA	V	0.2	0.6
	ICCH	High Level Supply Current, VCC = 5.5 V, VE = 0.5 V, IF = 0	mA	5	10
	ICCL	Low Level Supply Current, VCC = 5.5 V, VE = 2 V, IF = 10 mA	mA	10	18
	IEH	High Level Enable Current, VCC = 5.5 V, VEH = 2 V	mA	-0.7	-1.5
	IEL	Low Level Enable Current, VCC = 5.5 V, VEL = 0.5 V	mA	-1	-2
Coupled	IFHL	Threshold Input Current, High → Low VCC = 5 V, VE = 2 V, TA = -40 to +85 °C, VO = 0.8 V, RL = 350 Ω	mA	0.5	5
	R1-2	Isolation Resistance, Vin-out = 1 k VDC, RH 40 to 60 %	Ω	10 ¹¹	
	C1-2	Isolation Capacitance, V = 0, f = 1 MHz	pF	0.6	
	tPHL	Propagation Delay Time ¹ , High → Low, VCC = 5 V, IF = 7.5 mA, RL = 350 Ω, CL = 15 pF	ns	50	75
	tPLH	Propagation Delay Time ¹ , Low → High, VCC = 5 V, IF = 7.5 mA, RL = 350 Ω, CL = 15 pF	ns	50	75
	tr	Rise Time, VCC = 5 V, IF = 7.5 mA, RL = 350 Ω, CL = 15 pF	ns	20	
	tf	Fall Time, VCC = 5 V, IF = 7.5 mA, RL = 350 Ω, CL = 15 pF	ns	10	
	TEHL	Enable Propagation ² , Delay Time, High → Low VCC = 5 V, IF = 7.5 mA, VEH = 3 V, VEL = 0.5 V, RL = 350 Ω, CL = 15 pF	ns	10	
	TELH	Enable Propagation ² , Delay Time, Low → High VCC = 5 V, IF = 7.5 mA, VEH = 3 V, VEL = 0.5 V, RL = 350 Ω, CL = 15 pF	ns	25	

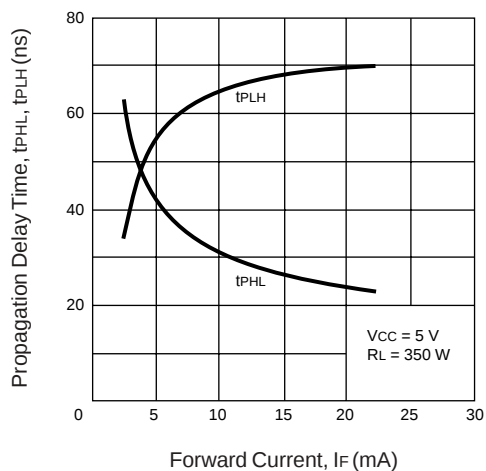
Notes: See Next Page

PART NUMBER			PS9601,PS9601L		
SYMBOLS	PARAMETERS	UNITS	MIN	TYP	MAX
IFL	Low Level Input Current	μA	0		250
IFH	High Level Input Current	mA	7	10	15
VEH	High Level Enable Voltage	V	2		VCC
VEL	High Level Enable Voltage	V	0		0.8
VCC	Supply Voltage	V	4.5	5	5.5
TOP	Operating Temperature	°C	0	25	70

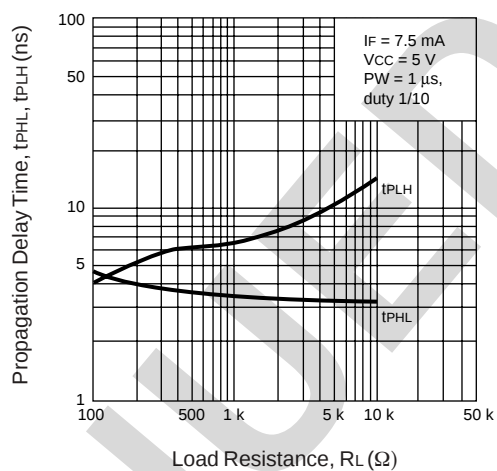
TYPICAL PERFORMANCE CURVES ($T_A = 25\text{ }^{\circ}\text{C}$)MAX. FORWARD CURRENT
vs. AMBIENT TEMPERATUREPOWER DISSIPATION vs.
AMBIENT TEMPERATUREFORWARD CURRENT vs.
FORWARD VOLTAGETHRESHOLD CURRENT vs.
AMBIENT TEMPERATUREOUTPUT VOLTAGE vs.
FORWARD VOLTAGELOW LEVEL OUTPUT VOLTAGE
vs. AMBIENT TEMPERATURE

TYPICAL PERFORMANCE CURVES ($T_A = 25^\circ\text{C}$)

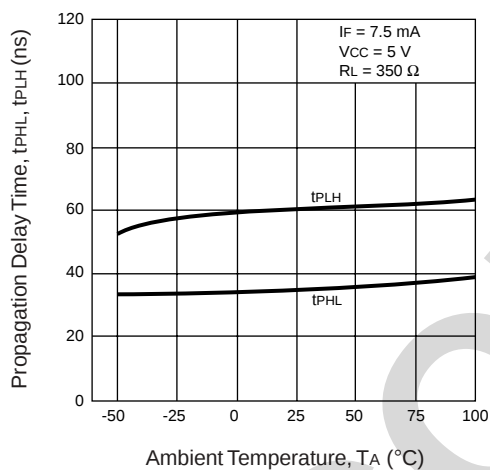
PROPAGATION DELAY TIME
vs. FORWARD CURRENT



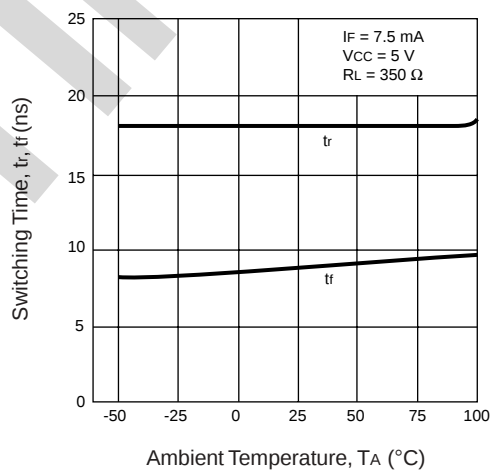
PROPAGATION DELAY TIME
vs. LOAD RESISTANCE



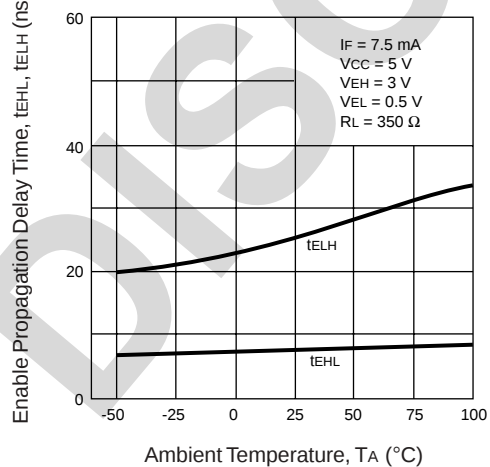
PROPAGATION DELAY TIME
vs. AMBIENT TEMPERATURE



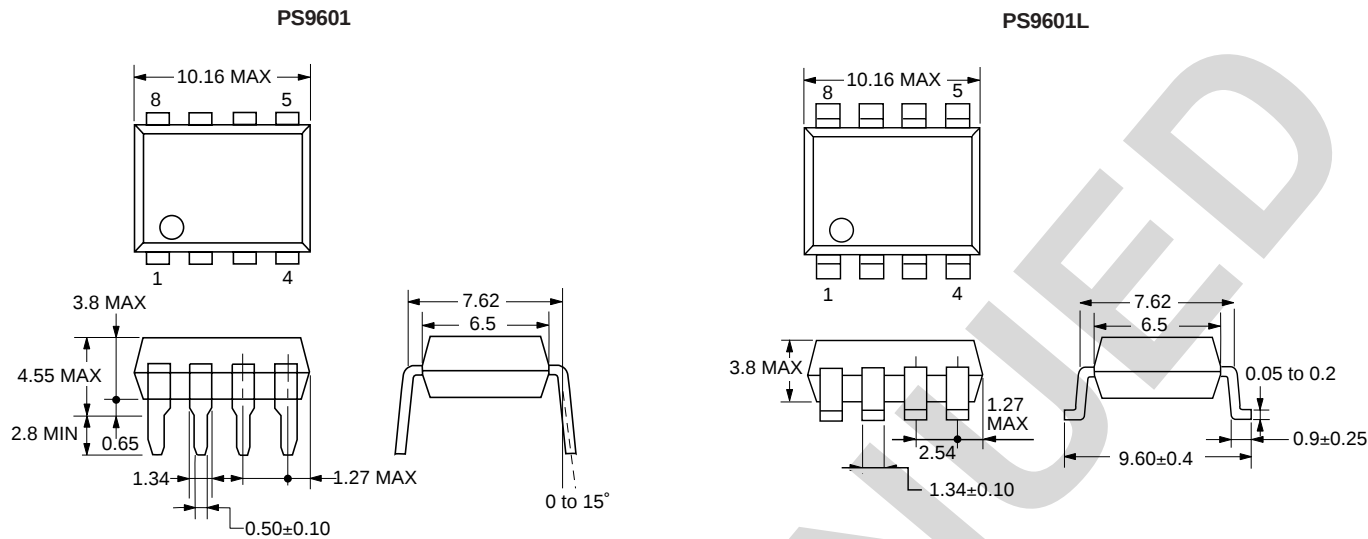
SWITCHING TIME vs.
AMBIENT TEMPERATURE



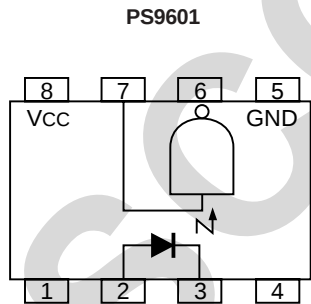
ENABLE PROPAGATION DELAY TIME
vs. AMBIENT TEMPERATURE



OUTLINE DIMENSIONS (Units in mm)



PIN CONNECTION (Top View)



	PIN	Function
INPUT	1.	NC
	2.	Anode
	3.	Cathode
	4.	NC
OUTPUT	5.	GND
	6.	Vo
	7.	VE*
	8.	VCC

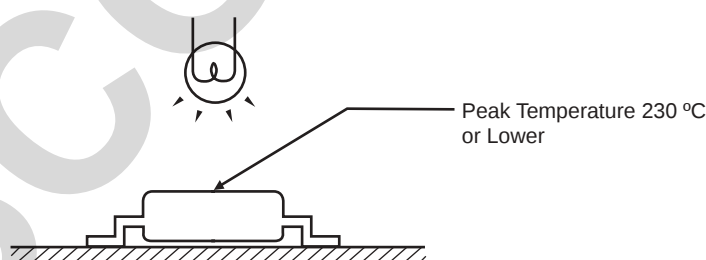
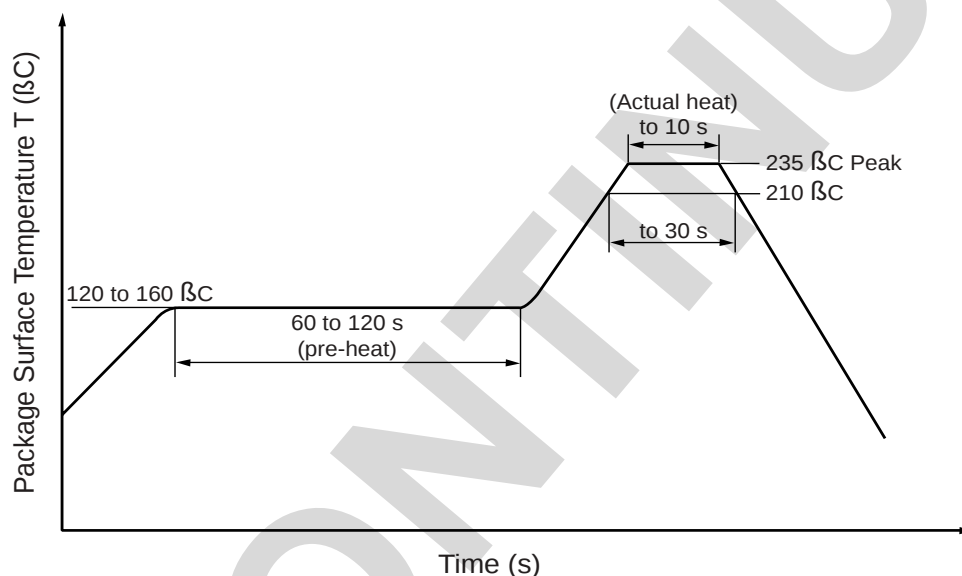
*VE is pulled - up to enable operation

RECOMMENDED SOLDERING CONDITIONS

(1) Precautions in mounting the devices by infrared reflow soldering

- **Peak reflow temperature**
235 °C or below (plastic surface temperature)
- **Reflow time**
30 seconds or less (Time period during which the plastic surface temperature is 210 °C)
- **Number of reflows Processes**
One
- **Flux**
Rosin flux containing small amount of chlorine (The flux with a max. chlorine content of 0.2 Wt % is recommended.)

INFRARED RAY REFLOW TEMPERATURE PROFILE



(2) Precautions in mounting the devices in solder dip method

- **Temperature**
260 °C or below
- **Time**
10 seconds or less
- **Flux**
Rosin group flux, where the amount of chloride component is small.